



Material Content Data Sheet



Sales Product Name				BTS426L1 E3062A		Issued		25. January 2018	
MA#				MA001118866					
Package				PG-TO263-5-2		Weight*		1497.48 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.039	0.34	0.34	3365	3365	
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158		
	non noble metal	iron	7439-89-6	0.790	0.05		527		
	non noble metal	copper	7440-50-8	788.527	52.64	52.71	526570	527255	
	non noble metal	aluminium	7429-90-5	1.577	0.11	0.11	1053	1053	
wire	non noble metal	aluminium	7429-90-5	1.577	0.11	0.11	1053	1053	
encapsulation	organic material	carbon black	1333-86-4	6.330	0.42		4227		
	inorganic material	antimonytrioxide	1309-64-4	13.235	0.88		8838		
	plastics	brominated resin	-	14.962	1.00		9991		
	plastics	epoxy resin	-	109.335	7.30		73013		
	inorganic material	silicondioxide	60676-86-0	431.585	28.82	38.42	288208	384277	
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6905	6905	
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5		
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2285	2290	
solder	non noble metal	tin	7440-31-5	0.080	0.01		54		
	noble metal	silver	7440-22-4	0.100	0.01		67		
	non noble metal	lead	7439-92-1	3.830	0.26	0.28	2557	2678	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		22		
	non noble metal	iron	7439-89-6	0.108	0.01		72		
	non noble metal	copper	7440-50-8	107.943	7.21	7.22	72083	72177	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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